

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC190N12NS3 G	**Issued**	22. January 2018
MA#	MA001638082		
Package	PG-TDSON-8-39	**Weight***	112.81 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	1.99	1.99	19920	19920
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		130	
	non noble metal	iron	7439-89-6	0.049	0.04		432	
	non noble metal	copper	7440-50-8	48.649	43.13	43.18	431239	431801
wire	non noble metal	copper	7440-50-8	0.043	0.04	0.04	379	379
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		725	
	plastics	epoxy resin	-	6.459	5.72		57250	
	inorganic material	silicondioxide	60676-86-0	34.337	30.44	36.23	304368	362343
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13474	13474
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1405	1405
solder	non noble metal	tin	7440-31-5	0.043	0.04		385	
	noble metal	silver	7440-22-4	0.054	0.05		481	
	non noble metal	lead	7439-92-1	2.075	1.84	1.93	18392	19258
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1330	
	non noble metal	copper	7440-50-8	16.910	14.99	15.14	149895	151420
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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